

L Number	Hits	Search Text	DB	Time stamp
1	29	(UBM or (under adj bump adj metallurgy)) and (polyimide with (opening or mask))	USPAT; US-PGPUB	2003/07/09 15:42
2	1	(UBM or (under adj bump adj metallurgy)) and (polyimide with (opening or mask))	EPO; JPO; DERWENT; IBM_TDB	2003/07/09 13:51
3	9	(taiwan adj semiconductor) and (UBM or (under adj bump adj metallurgy)) and polyimide	USPAT; US-PGPUB	2003/07/09 14:43
4	4	((taiwan adj semiconductor) and (UBM or (under adj bump adj metallurgy)) and polyimide) not ((UBM or (under adj bump adj metallurgy)) and (polyimide with (opening or mask)))	USPAT; US-PGPUB	2003/07/09 14:42
5	0	(taiwan adj semiconductor) and (UBM or (under adj bump adj metallurgy)) and polyimide	EPO; JPO; DERWENT	2003/07/09 14:43
6	108	sputtering with (UBM or (under adj bump adj metallurgy))	USPAT; US-PGPUB	2003/07/09 15:02
7	57	(sputtering with (UBM or (under adj bump adj metallurgy))) and @ad<=20010215	USPAT; US-PGPUB	2003/07/09 15:43
8	92	(UBM or (under adj bump adj metallurgy)) and stencil	USPAT; US-PGPUB	2003/07/09 15:43
9	50	((UBM or (under adj bump adj metallurgy)) and stencil) and @ad<=20010215	USPAT; US-PGPUB	2003/07/09 15:55
10	50	((UBM or (under adj bump adj metallurgy)) and stencil) and @ad<=20010215	USPAT; US-PGPUB	2003/07/09 16:05
11	23	((UBM or (under adj bump adj metallurgy)) and stencil) and @ad<=20010215) and screen	USPAT; US-PGPUB	2003/07/09 16:05

L Number	Hits	Search Text	DB	Time stamp
1	70	(UBM or (under adj bump adj metallurgy)) and (etching with pad)	USPAT; US-PGPUB	2003/07/09 18:12
2	33	((UBM or (under adj bump adj metallurgy)) and (etching with pad)) and @ad<=20010215	USPAT; US-PGPUB	2003/07/09 18:10
3	4	(UBM or (under adj bump adj metallurgy)) and (etching with pad)	EPO; JPO; DERWENT; IBM TDB	2003/07/09 18:13